【ISSM2026Sponsorship Selection and Benefits】

Level	**Platinum**	**Gold**	**Silver**	**Bronze**	**Refreshment**	**Lanyard**
Maximum number of sponsors	—	—	—	—	2	1
Sponsorship fee (10% tax to be added)	¥800,000	¥600,000	¥400,000	¥200,000	¥200,000	¥200,000
Participation to ISSM 2026						
Free tickets to ISSM 2026	6	4	2	1	1	1
Visibility						
Logo on ISSM2026 website	Yes	Yes	Yes	Yes	Yes	Yes
1-min PR movie prior to keynote speech	Yes	Yes				
Logo appeared on online proceedings	Yes	Yes	Yes	Yes	Yes	Yes
Logo appeared on interval screen	Yes	Yes	Yes	Yes	Yes	Yes
Logo on sponsorship banner at the venue	Yes	Yes	Yes	Yes	Yes	Yes
Logo at refreshment table					Yes	
Company name on lanyard						Yes
Provision of Exhibition Space						
Exhibit Space Table: W1800 × D450 × H720 mm Back Panel: W900 × H1800 mm (three panels connected) Power Supply: An additional fee of JPY 6,000 (10% tax to be added) is required if a power supply (100V, 500W) is requested. Tablecloth: Not provided. Exhibition Period: Two days Day 1: Starts at approximately 10:30 Final Day: Ends at approximately 15:00	Yes	Yes	Yes	Yes		

JPY50,000 discount applied for the original strap(250pcs)

Note

*Exhibition space is available on a first-come, first-served basis, as the number of spaces that can be installed is limited.

*The deadline for logo inclusion on posters is the end of October 2026.

*Application deadline: End of October 2026.

(Please note that Refreshment Sponsors and Lanyard Sponsors, for which the number of available slots is limited, will be accepted on a first-come, first-served basis and may close earlier once capacity is reached.)

■Contact
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ISSM2026 Outline

1. Conference Name
   International Symposium on Semiconductor Manufacturing 2026 (ISSM2026)

2. Sponsor
   Co-sponsored by:
   - Minimal Fab
   - Semiconductor Equipment Association of Japan (SEAJ)
   - Semiconductor Equipment and Materials International (SEMI)
   - Taiwan Semiconductor Industry Association (TSIA)

   Technical Sponsored by:
   - IEEE Electron Devices Society

   Endorsement by:
   - The Japan Society of Applied Physics

3. Date
   Date：December 7-8, 2026

4. Venue
   KFC(Kokusai Fashion Center) Hall
   1-6-1 Yokoami Sumida-ku,Tokyo 130-0015 Japan
   +81-3-5610-5810

5. Program
   ISSM2026 plans to include:
   - Keynote speeches
   - Tutorial sessions
   - Highlighted sessions
   - Oral presentation by selected authors
   - Poster presentation by selected authors

6. Conference Areas
   Fab Management
   * Factory Design (FD)
   * Manufacturing Strategy (MS)
   * Manufacturing Control and Execution (MC)
   * Environment, Safety and Health, Carbon Neutral (ES)
   * Intelligent Data Management (ID)

   Process Integration
   * Process/Material Optimization (PO)
   * Yield Enhancement and Methodology (YE)
   * Ultraclean Technology and Contamination Control (UC)
   * Process Monitoring and Control Method (PC)
   * Process/Metrology Equipment (PE)
   * Design for Manufacturing (DM)
   * Innovative manufacturing technology(IM)

   3D, Chiplets Packaging & Advanced Packaging
   *3D Integration, Chiplets Packaging and Advanced Packaging Technology (TP)

7. Highlight Themes
   Robotics and AI Solution
      – Autonomous Fab control by Big Data Science
      – Advanced Material handling system, Automation of Maintenance
      – Nobel sensing and data processing using AI/ML
   Next Generation Fab
      – Smart Factory and GX
      – Sophisticated Transportation including PKG
      – Physical Analysis Automation and Short Development Period

   Sustainable Manufacturing and Promotion of Global Environmental Conservation
      – High Energy Efficiency and Emission Reduction
      – Return of Investment in Legacy Fab.
      Exploring New Frontiers from Chip Design to Testing: 3D and Chiplets Packaging
      – Glass substrate/TGV/Si bridge, 3D interconnection/hybrid bonding/Cu-Cu direct bonding, Interlayer dielectric materials/Sub-micron fine circuit formation technology, Chiplets Packaging technology, Module testing technology
8. Expected Participants
   250
9. Conference Official Language
   English
      Presentation: English
      Handout/Materials: English